

CHANGE NOTIFICATION

NOW PART OF



Analog Devices, Inc.
1630 McCarthy Blvd., Milpitas CA
(408) 432-1900

September 07, 2018

PCN_090718

Dear Sir/Madam:

Subject: Notification of Wafer Fab Location Change for LT8612

Please be advised that Analog Devices, Inc. Milpitas, California is planning to close our Wafer Fab facility located at 275 S. Hillview Dr., Milpitas, CA in February 2021. Due to this future closure of Wafer Fab facility, the device LT8612 manufactured using 0.35 BCD process will be affected and transferred to Vanguard International Semiconductor, Taiwan as part of expanding our business partnership. Vanguard International Semiconductor third party certifications and capacity details are attached for your review. Additional information can be found at <http://www.vis.com.tw>.

The qualification of the Vanguard International Semiconductor consisted of 1,000 hours of op-life testing, temp cycle, highly accelerated stress test, autoclave, and 1,000 hours of bake at 150°C. The devices have been characterized over the full operating temperature range and have been subjected to ESD testing and latch up immunity testing. The devices have been found to meet the ADI data sheets. Additionally, devices from the Vanguard International Semiconductor were carefully compared to the ADI fabricated devices to ensure identical performance when installed in customer applications.

Affected Part Number	
1	LT8612EUDE#PBF
2	LT8612IUDE#PBF
3	LT8612EUDE#TRPBF
4	LT8612IUDE#TRPBF

The devices manufactured in Vanguard International Semiconductor will have the same part number and the same top mark as those manufactured at ADI. However, when necessary we can use our lot number traceability system to identify where and when a device was fabricated.

Analog devices will accept sample requests for parts built at Vanguard Semiconductor International within 30 days of the date of this notification. If we do not hear back from your company within 30-day period, we will consider this change notice accepted by November 07, 2018. Production shipments of the products built at Vanguard Semiconductor International will begin no sooner than November 07, 2018.

Should you have any questions or concerns please contact your local Analog Devices sales representatives or you may contact me at 408-432-1900 ext. 2077, or by e-mail at JASON.HU@ANALOG.COM. If I do not hear from you by November 07, 2018, we will consider this change to be approved by your company.

Sincerely,

Jason Hu
Quality Assurance Engineer

For questions on this PCN, please contact Jason Hu or you may send an email to your regional contacts below or contact your local ADI sales representatives.			
Americas: PCN_Americas@analog.com	Europe: PCN_Europe@analog.com	Japan: PCN_Japan@analog.com	
		Rest of Asia: PCN_ROA@analog.com	



Vanguard International Semiconductor Corporation

Vanguard International Semiconductor Summary

- Plant Address
123, Park Ave-3rd, Science-Based Industrial Park, Hsinchu, Taiwan 30077, R.O.C.
- Headcount
5,200
- Total Building size in sq. ft. and fab size in sq. meters
880,543.3 sq. feet (Building 1)
- Clean room floor space in sq. meters
12,600 sq. meters (Building 1)
- Fab utilization in percent
Fab 1: 100%
- Land Area in sq. meters
41,925 sq. meters
- Wafer capacity for each facility
Fab 1: 87K wafers per month (ADI's material is scheduled to run in Fab 1)
- A list of certifications (i.e. TS16949, ISO-14001, etc.)
 - ISO 9001 Quality Management System (since 1996)
 - ISO 14001 Environment Management System (since 1997)
 - OHSAS 18001 Health & Safety Management System (since 2003)
 - QC 080000 Hazardous Substance Management System (since 2007)
 - ISO 27001 Information Security Management System (since 2015)
 - IATF 16949 Automotive Quality Management System (since 2018)



RELIABILITY DATA
LT8612 Fab Transfer
9/5/2018

• OPERATING LIFE TEST					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS AT +150°C	NUMBER OF FAILURES
QFN	231	1738	1810	231	0
Total	231			231	0
• HIGHLY ACCELERATED STRESS TEST (HAST) AT +130°C / 85%RH					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	Equivalent K DEVICE HOURS AT +85°C	NUMBER OF FAILURES
QFN	240	1738	1810	921.6	0
Total	240			921.6	0
• PRESSURE COOKER TEST (PCT) AT 15PSIG, +121°C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS	NUMBER OF FAILURES
QFN	231	1738	1810	77.616	0
Total	231			77.616	0
• TEMPERATURE CYCLE (TC) TEST AT -65°C to +150°C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
QFN	241	1738	1810	395	0
Total	241			395	0
• THERMAL SHOCK (TS) TEST AT -65°C to +150°C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
QFN	234	1738	1810	468	0
Total	234			468	0
• HIGH TEMPERATURE STORAGE LIFE TEST AT +150°C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS	NUMBER OF FAILURES
QFN	154	1751	1810	154	0
Total	154			154	0
• SOLDER SHOCK TEST 3H PCT plus 1x SOLDER IMMERSION at 245°C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE		NUMBER OF FAILURES
QFN	143	1738	1810		0
Total	143				0
(1) Sample size too small for meaningful FIT calculations. (2) Failure Rate Equivalent to +55C, Assuming 60% Confidence Level & Activation Energy of 0.7eV = 15.3FIT (3) Mean Time Between Failures (MTBF) = 7,480 yr Assumes 20X acceleration from +85°C to +130°C. Note: HAST, PCT, and TC tests are preceded by JEDEC Preconditioning: 168h 85°C/85% R.H. plus 3x IR at 260°C Note: 1 FIT = 1 Failure in One Billion Hours.					